

Spec. No. : Preliminary Data Issued Date : 1999.03.01 Revised Date : 2000.11.01

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HJ6668

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HJ6668 is designed for general-purpose amplifier and switching applications.

Absolute Maximum Ratings (Ta=25°C)

Maximum Temperatures	
Storage Temperature	55 ~ +150 °C
Junction Temperature	+150 °C Maximum
Maximum Power Dissipation	
Total Power Dissipation (Tc=25°C)	65 W
Maximum Voltages and Currents	
BVCBO Collector to Base Voltage	80 V
BVCEO Collector to Emitter Voltage	80 V
BVEBO Emitter to Base Voltage	5 V
IC Collector Current	10 A

Characteristics (Ta=25°C)

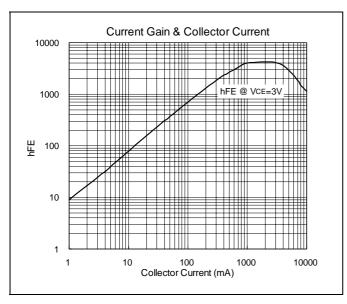
Symbol	Min.	Тур.	Max.	Unit	Test Conditions	
BVCBO	-80	-	-	V	IC=-10mA	
BVCEO	-80	-	-	V	IC=-200mA	
IEBO	-	-	-100	mA	VEB=-5V	
ICEO	-	-	-1	mA	VCE=-80V	
ICEV	-	1	-300	uA	VCE=-80V, VBE(off)=-1.5V	
*VCE(sat)1	-	-	-2	V	IC=-5A, IB=-10mA	
*VCE(sat)2	-	-	-3	V	IC=-10A, IB=-100mA	
*VBE(on)1	-	-	-2.8	V	IC=-5A, VCE=-3V	
*VBE(on)2	-	-	-4.5	V	IC=-10A, VCE=-3V	
*hFE1	1	-	20	K	IC=-5A, VCE=-3V	
*hFE2	100	-	-		IC=-10A, VCE=-3V	

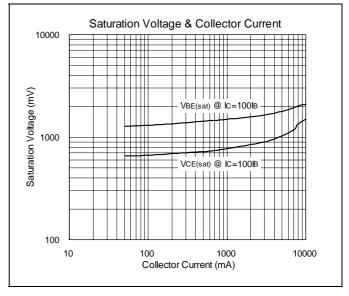
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

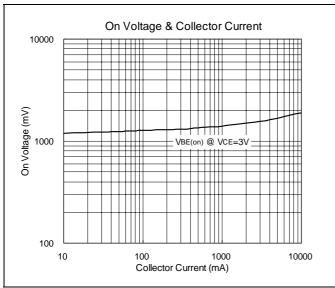
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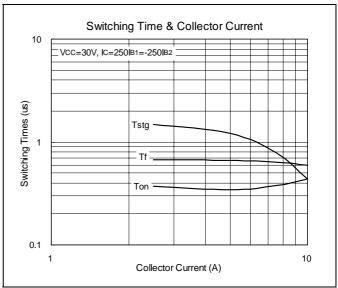
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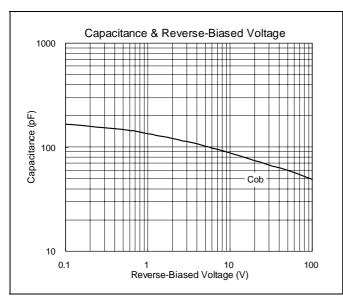
Characteristics Curve







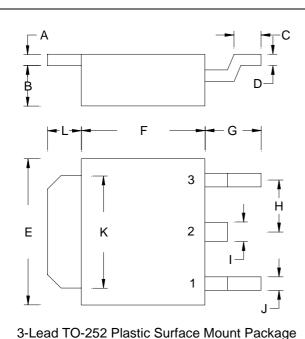




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TO-252 Dimension



HSMC Package Code: J

Style : Pin 1.Base 2.Collector 3.Emitter

Marking:

HSMC Logo Product Series

Part Number Rank

Date Code Ink Mark

*:Typical

DIM -	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.	DIIVI	Min.	Max.	Min.	Max.
Α	0.0177	0.0217	0.45	0.55	G	0.0866	0.1102	2.20	2.80
В	0.0650	0.0768	1.65	1.95	Ι	-	*0.0906	•	*2.30
С	0.0354	0.0591	0.90	1.50	ı	-	0.0354	•	0.90
D	0.0177	0.0236	0.45	0.60	J	-	0.0315	-	0.80
Е	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2125	0.2283	5.40	5.80	L	0.0551	0.0630	1.40	1.60

Notes: 1.Dimension and tolerance based on our Spec. dated May. 05,1996.

- 2. Controlling dimension: millimeters.
- 3. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
- 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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